

# PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Kim-Yong Goh	01/13/2010
RECEIVING PARTY DATA	
Name:	STMicroelectronics Asia Pacific PTE, Ltd.
Street Address:	5A Serangoon North Avenue 5
City:	Singapore
State/Country:	SINGAPORE
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12651295
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ATTORNEY DOCKET NUMBER:	851663.501
NAME OF SUBMITTER:	Michael Murphy
Total Attachments: 2 source=851663_501_ASSIGN#page1.tif source=851663_501_ASSIGN#page2.tif	

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 REEL: 024100 FRAME: 0643

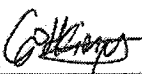
## ASSIGNMENT

WHEREAS, I, Kim-Yong Goh (hereinafter referred to as ASSIGNOR), having a mailing address of Blk 688B, Choa Chu Kang Drive, #11-332, Singapore, Singapore 682688, am the sole inventor of an invention entitled "FAN-OUT WAFER LEVEL PACKAGE WITH POLYMERIC LAYER FOR HIGH RELIABILITY," as described and claimed in the specification for which an application for United States letters patent was filed on December 31, 2009, and assigned Application No. 12/651,295;


WHEREAS, STMicroelectronics Asia Pacific PTE, Ltd. (hereinafter referred to as ASSIGNEE), a corporation of the Country of Singapore having a place of business at 5A Serangoon North Avenue 5, Singapore, Singapore 554574, is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefor in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR hereby sells, assigns and transfers unto said ASSIGNEE the entire right, title and interest in and to said invention, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions including any extensions or adjustments in term thereof and in any and all foreign countries, and in any and all divisions, reissues and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR had this assignment, transfer and sale not been made. ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR agrees to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefor.

13-Jan-2010  
Date

  
Kim-Yong Goh

I certify that I know or have satisfactory evidence that Kim-Yong Goh is the person who appeared before me, and said person acknowledged that he signed this instrument and acknowledged it to be his/her free and voluntary act for the uses and purposes mentioned in the instrument.

Dated 13-Jan-2010  
Signature of  
Witness   
Printed Name Hu Guojun

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